



## Staff Engineer - Package Technology

### Job description

Drive Technology Integration activities to ensure the package fulfill all requirements in the aspect of Process Interaction. Key working partner for FE colleagues for new FE technology.

In your new role you will:

- Responsible in PBC and TPC assessment
- Be the driver of Package Technology DFMEA
- Be the owner of Risk Interaction assessment and mitigation work packages
- Be the working partner for FE in FE/BE interaction and integration topics
- Support Pre development for new Chip technology
- Be the diver/team member for 8D/problem solving for interaction issues
- Assess the impact of design rules on inter-process interaction
- Provide Technical guidance/assistance when needed in the projects related to interaction topic

### Profile

You are best equipped for this task if you have:

- Bachelor's Degree in Engineering (Semiconductor Technology, Microelectronics, Automation, Mechanical, Electrical, Electronics Physics)
- At least 5 years of working experience in IC/semiconductor environment
- Semiconductor Packaging, Assembly and Test knowledge
- Good aptitude for communication, collaboration, negotiation and solution finding
- Internal Package analysis/ first level reliability
- Experience in 8D & T6s methodology

### At a glance

Location: **Melaka**  
Job ID: **306799**  
Start date: **immediately**  
Entry level: **6+ years**  
Type: **Full time**  
Contract: **Permanent**

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